L Number	Hits	Search Text	DB	Time stamp
1	8	("4149310" "5249101" "5903046")[pn]	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/06/11 20:31
-	0	low with modulus with high with enlongat$ with dielectric	USPAT; US-PGPUB	2001/06/07 18:55
-	0	low same modulus same high same enlongat$ same dielectric	USPAT; US-PGPUB	2001/06/07 18:56
-	0	modulus with enlongat$ with dielectric	USPAT; US-PGPUB	2001/06/07 18:56
-	21	modulus with strain with dielectric	USPAT; US-PGPUB	2001/06/07 18:57
-	41	modulus with stress with dielectric	USPAT; US-PGPUB	2001/06/07 19:19
-	83	thermal adj expansion adj coefficient with dielectric and (257/$ 438/$)	USPAT; US-PGPUB	2001/06/07 20:24
-	1	5841193.pn.	USPAT; US-PGPUB	2001/06/07 20:30
-	9	("4630096" | "4827328" | "4860166" | "4907062" | "5049980" | "5091769" | "5111278" | "5250843" | "5315486").PN.	USPAT	2001/06/07 20:24
-	2	5841193.URPN.	USPAT	2001/06/07 20:24
-	30	FR4 adj circuit adj board	USPAT; US-PGPUB	2001/06/07 20:37
-	554	(printed adj circuit adj board PCB) same solder adj balls and (257/$.ccls. 438/$.ccls.)	USPAT; US-PGPUB	2001/06/07 20:39
-	50	FR4 adj printed adj circuit adj board	USPAT; US-PGPUB	2001/06/07 21:05
-	202	eichelberger.in.	USPAT; US-PGPUB	2001/06/07 21:06
-	40	eichelberger.in. and (257/$ 438/$)	USPAT; US-PGPUB	2001/06/07 21:09
-	0	(eichelberger.in. and (257/$ 438/$)) and enlongat$	USPAT; US-PGPUB	2001/06/07 21:09
-	0	eichelberger.in. and enlongat$	USPAT; US-PGPUB	2001/06/07 21:11
-	14	eichelberger.in. and thermal adj expansion	USPAT; US-PGPUB	2001/06/07 21:49
-	0	(eichelberger.in. and thermal adj expansion) and modulus	USPAT; US-PGPUB	2001/06/07 21:12
-	0	(eichelberger.in. and thermal adj expansion) and modulus	USPAT; US-PGPUB	2001/06/07 21:12
-	288	expansion same modulus same dielectric	USPAT; US-PGPUB	2001/06/07 21:49
-	47	(expansion same modulus same dielectric) and (257/$ 438/$)	USPAT; US-PGPUB	2001/06/07 22:27
-	17	low adj modulus same (CTE expansion enlongation fracute) same dielectric	USPAT; US-PGPUB	2001/06/07 22:29
-	19	low adj modulus same (CTE expansion enlongation fracture) same dielectric	USPAT; US-PGPUB	2001/06/07 22:33
-	2	(low adj modulus same (CTE expansion enlongation fracture) same dielectric) not (low adj modulus same (CTE expansion enlongation fracute) same dielectric)	USPAT; US-PGPUB	2001/06/07 22:35
-	0	low adj modulus same high adj enlongation	USPAT; US-PGPUB	2001/06/07 22:35
-	0	low adj modulus same enlongation	USPAT; US-PGPUB	2001/06/07 22:35
-	0	low adj modulus and enlongation	EPO; JPO; DERWENT; IBM TDB	2001/06/07 22:36
-	555	low adj modulus and fracture	USPAT; US-PGPUB	2001/06/07 22:36
-	18	low adj modulus and fracture	EPO; JPO; DERWENT; IBM TDB	2001/06/07 22:36

C:\APPS\EAST\workspaces\%09502078.wsp

-	64	low adj modulus same fracture	USPAT; US-PGPUB	2001/06/07 22:46
-	611	low adj modulus same elongation	USPAT; US-PGPUB	2001/06/07 22:47
-	5	low adj modulus same elongation same dielectric	USPAT; US-PGPUB	2001/06/07 22:48
-	5	low adj modulus and elongation and dielectric	EPO; JPO; DERWENT; IBM TDB	2001/06/07 22:52
-	51	modulus and elongation and dielectric	EPO; JPO; DERWENT; IBM TDB	2001/06/07 22:52
-	1427	modulus and elongation and dielectric	USPAT; US-PGPUB	2001/06/07 22:52
-	247	modulus same elongation same dielectric	USPAT; US-PGPUB	2001/06/07 22:52
-	6	(modulus same elongation same dielectric) and (257/$ 438/$)	USPAT; US-PGPUB	2001/06/07 23:20
-	699	acrylated adj urethane	USPAT; US-PGPUB	2001/06/07 23:20
-	8	(acrylated adj urethane) and (257/$ 438/$)	USPAT; US-PGPUB	2001/06/07 23:39
-	0	lenght with displac$ and (257/$ 438/$)	USPAT	2001/06/08 00:24
-	79	long with displac$ and (257/$ 438/$)	USPAT	2001/06/08 00:42
-	246	length with displac$ and (257/$ 438/$)	USPAT	2001/06/08 00:44
-	18	length with displac$ with (wir$ conductor interconnect) and (257/$ 438/$)	USPAT	2001/06/08 20:53
-	23	length with displac$ with (wir$ conductor interconnect) and (257/$ 438/$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/06/08 13:40
-	1	5903046.pn. and modulus	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/06/08 16:33
-	1	5249101.pn. and (elongation fracture)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/06/08 16:52
-	0	5249101.pn. and dielectric	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/06/08 16:52
-	0	5249101.pn. and insulator	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/06/08 16:52
-	4	acrylated adj urethane with dielectric	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/06/08 16:55
-	0	(acrylated adj urethane with dielectric) and elongation	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/06/08 17:31
-	602	modulus with copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/06/08 17:32

-	0	modulus with copper adj interconnect	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/06/08 17:32
-	12	modulus with copper adj wire	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/06/08 17:36
-	49	(modulus with copper) and (257/$ 438/$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/06/08 20:26
-	13	(("Young's" "young") with modulus with copper) and (257/$ 438/$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/06/08 20:28
-	13	(("Young's" "young's") with modulus with copper) and (257/$ 438/$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/06/08 20:30
-	13	(("Young" "young") with modulus with copper) and (257/$ 438/$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/06/08 20:31
-	23	length with displac$ with (wir$ conductor interconnect) and (257/$ 438/$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/06/08 21:15
-	12	expansion with (wir$ conductor interconnect) with displac$ and (257/$ 438/$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/06/08 21:35
-	17	expansion with (wir$ conductor interconnect) same displac$ and (257/$ 438/$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/06/08 21:43
-	5	(expansion with (wir$ conductor interconnect) same displac$ and (257/$ 438/$)) not (expansion with (wir$ conductor interconnect) with displac$ and (257/$ 438/$))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/06/08 21:41
-	15	expansion same (wir$ conductor interconnect) same length same displac$ and (257/$ 438/$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/06/08 21:49
-	11	(expansion same (wir$ conductor interconnect) same length same displac$ and (257/$ 438/$)) not ((expansion with (wir$ conductor interconnect) same displac$ and (257/$ 438/$)) not (expansion with (wir$ conductor interconnect) with displac$ and (257/$ 438/$))) not (expansion with (wir$ conductor interconnect) same displac$ and (257/$ 438/$))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/06/08 21:51
-	100	thermal adj expansion with displac$ and (257/$ 438/$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/06/09 00:56

-		3	5841193.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/06/11 20:30